

ABSTRACT OF THE DISCLOSURE

A semiconductor package assembly is disclosed having a semiconductor die receiving member configured to accept a semiconductor die in either the flip-chip or the wirebond orientations. First contact sites on a die receiving surface provide electrical connection with a flip-chip component. Second contact sites provide electrical connection with a wirebond component. Electrically conductive traces connect the first and second contact sites with terminal contact sites. The semiconductor package assembly may further include the flip-chip or wirebond component mounted over the die receiving surface. Further, the assembly may also include a mounting substrate in electrical connection with the terminal contact sites.

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